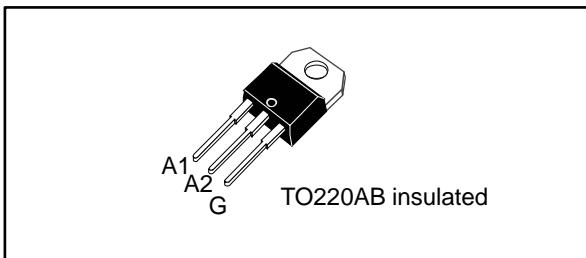


## 8 A Snubberless™ Triac

Datasheet - production data



### Features

- High static dV/dt
- High dynamic commutation
- 150 °C maximum  $T_j$
- Three quadrants
- Built-in ceramic for tab insulation
- Compliance to UL1557 standard (ref : E81734)
- ECOPACK®2 compliant component
- Complies with UL94,V0
- Surge capability  $V_{DSM}$ ,  $V_{RSM} = 900$  V

### Benefits

- Device is less likely to have false turn-on thanks to high dV/dt
- Better turn-off in high temperature environments thanks to  $(dI/dt)_c$
- Increase of thermal margin due to extended working  $T_j$  up to 150 °C
- Better thermal resistance due to the ceramic inside the package

### Applications

- General purpose AC line load switching
- Motor control circuits
- Home appliances
- Heating
- Lighting
- Inrush current limiting circuits
- Overvoltage crowbar protection

### Description

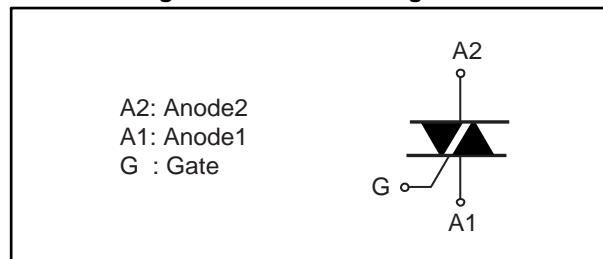
Available in through-hole package, the T835T-8I Triac can be used for the on/off or phase angle control function in general purpose AC switching where high commutation capability is required. This device can be used without a snubber RC circuit when the limits defined are respected.

TO-220AB insulated provides tab insulation, UL1557 certified, rated at 2.5 kV RMS and UL-94, V0 resin compliance.

Package environmentally friendly ECOPACK®2 graded (RoHS and Halogen Free compliance).

Snubberless™ is a trademark of STMicroelectronics.

**Figure 1: Functional diagram**



**Table 1: Device summary**

Symbol	Value	Unit
$I_{T(RMS)}$	8	A
$V_{DRM}/V_{RRM}$	800	V
$V_{DSM}/V_{RSM}$	900	V
$I_{GT}$	35	mA

# 1 Characteristics

Table 2: Absolute maximum ratings (limiting values)

Symbol	Parameter			Value	Unit
$I_{T(RMS)}$	RMS on-state current (full sine wave)		$T_c = 118^\circ\text{C}$	8	A
$I_{TSM}$	Non repetitive surge peak on-state current, $T_j$ initial = 25 °C		$t_p = 16.7 \text{ ms}$	63	A
			$t_p = 20 \text{ ms}$	60	
$I^2t$	$I^2t$ value for fusing, $t_p = 10 \text{ ms}$		$T_j$ initial = 25 °C	24	$\text{A}^2\text{s}$
$dl/dt$	Critical rate of rise of on-state current, $I_G = 2 \times I_{GT}$ , $t_r \leq 100 \text{ ns}$	$T_j = 150^\circ\text{C}$	$f = 100 \text{ Hz}$	100	$\text{A}/\mu\text{s}$
$V_{DRM}/V_{RRM}$	Repetitive peak off-state voltage		$T_j = 150^\circ\text{C}$	600	V
			$T_j = 125^\circ\text{C}$	800	V
$V_{DSM}/V_{RSM}$	Non Repetitive peak off-state voltage		$t_p = 10 \text{ ms}$	900	V
$I_{GM}$	Peak gate current	$t_p = 20 \mu\text{s}$	$T_j = 150^\circ\text{C}$	4	A
$P_{G(AV)}$	Average gate power dissipation		$T_j = 150^\circ\text{C}$	1	W
$T_{stg}$	Storage junction temperature range			-40 to +150	°C
$T_j$	Operating junction temperature range			-40 to +150	°C
$T_L$	Maximum lead temperature for soldering during 10 s			260	°C
$V_{ins}$	Insulation RMS voltage, 1 minute, UL1557 certified (E81734)			2.5	kV

Table 3: Electrical characteristics ( $T_j = 25^\circ\text{C}$ , unless otherwise specified)

Symbol	Test Conditions			Value	Unit
$I_{GT}^{(1)}$	$V_D = 12 \text{ V}$ , $R_L = 30 \Omega$		I - II - III	Min.	1.75 mA
	$V_D = 12 \text{ V}$ , $R_L = 30 \Omega$		I - II - III	Max.	35 mA
$V_{GT}$	$V_D = 12 \text{ V}$ , $R_L = 30 \Omega$		I - II - III	Max.	1.3 V
$V_{GD}$	$V_D = V_{DRM}$ , $R_L = 3.3 \text{ k}\Omega$ , $T_j = 150^\circ\text{C}$		I - II - III	Min.	0.2 V
$I_L$	$I_G = 1.2 \times I_{GT}$		I - III	Max.	60 mA
			II	Max.	70 mA
$I_H$	$I_T = 500 \text{ mA}$ , gate open			Max.	40 mA
$dV/dt$	$V_D = 536 \text{ V}$ , gate open	$T_j = 125^\circ\text{C}$	Min.	2000	$\text{V}/\mu\text{s}$
	$V_D = 402 \text{ V}$ , gate open	$T_j = 150^\circ\text{C}$		1000	$\text{V}/\mu\text{s}$
$(dl/dt)c$	Without snubber, $(dV/dt)c > 20 \text{ V}/\mu\text{s}$		$T_j = 125^\circ\text{C}$	Min.	8 $\text{A}/\text{ms}$
			$T_j = 150^\circ\text{C}$		4 $\text{A}/\text{ms}$

**Notes:**

<sup>(1)</sup>For both polarities of A2 referenced to A1.

**Table 4: Static characteristics**

<b>Symbol</b>	<b>Test conditions</b>	<b>T<sub>j</sub></b>		<b>Value</b>	<b>Unit</b>
V <sub>TM<sup>(1)</sup></sub>	I <sub>T</sub> = 11.3 A, t <sub>p</sub> = 380 µs	25 °C	Max.	1.60	V
V <sub>TO</sub>	Threshold on-state voltage	150 °C	Max.	0.87	V
R <sub>D</sub>	Dynamic resistance	150 °C	Max.	80	mΩ
I <sub>DRM</sub> /I <sub>RRM</sub>	V <sub>DRM</sub> = V <sub>RRM</sub> = 800 V	25 °C	Max.	5	µA
		125°C		1.0	mA
	V <sub>DRM</sub> = V <sub>RRM</sub> = 600 V	150 °C	Max.	2.5	mA

**Notes:**

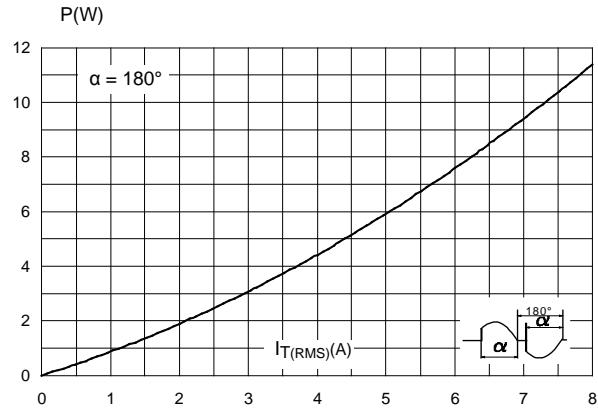
(1)For both polarities of A2 referenced to A1.

**Table 5: Thermal resistance**

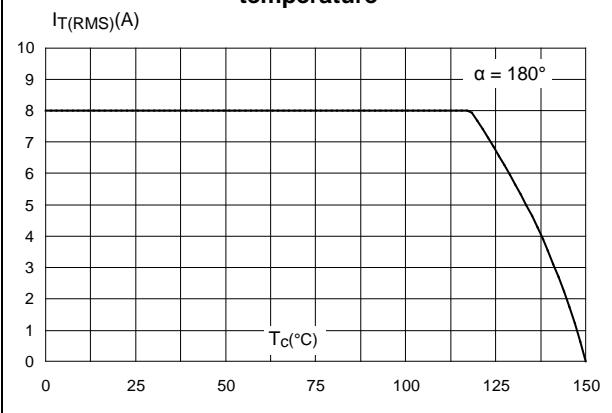
<b>Symbol</b>	<b>Parameter</b>		<b>Value</b>	<b>Unit</b>
R <sub>th(j-c)</sub>	Junction to case (AC)	Max.	2.8	°C/W
R <sub>th(j-a)</sub>	Junction to ambient		60	

## 1.1 Characteristics (curves)

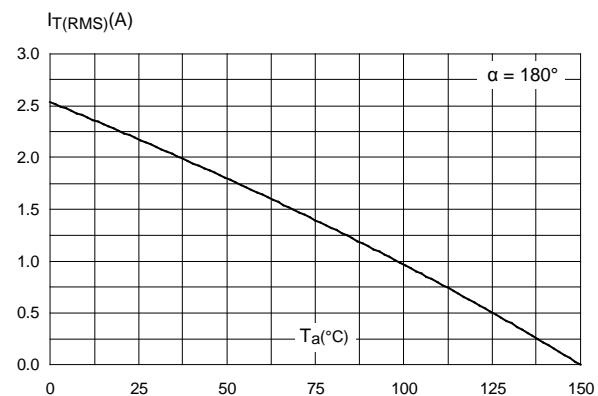
**Figure 2: Maximum power dissipation versus on-state RMS current**



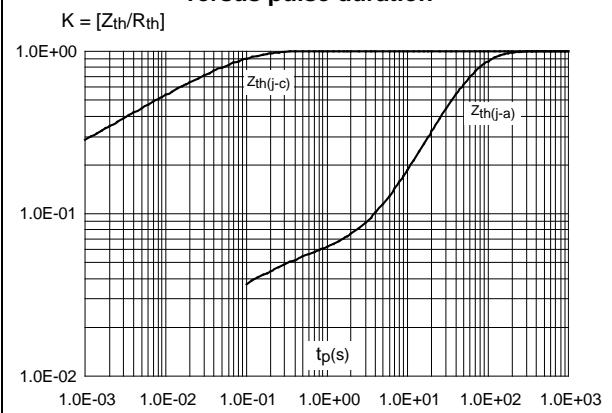
**Figure 3: On-state RMS current versus case temperature**



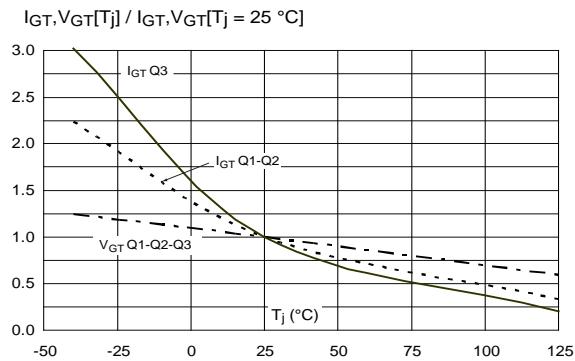
**Figure 4: On-state RMS current versus ambient temperature (free air convection)**



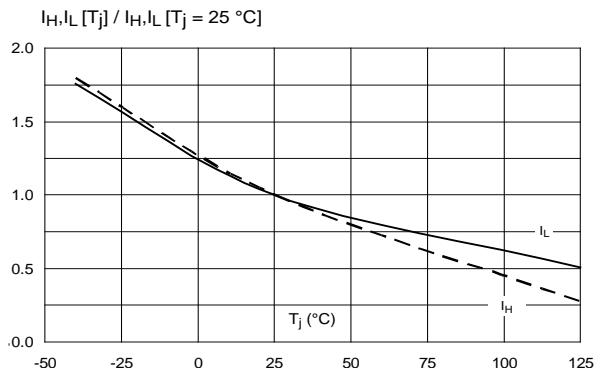
**Figure 5: Relative variation of thermal impedance versus pulse duration**



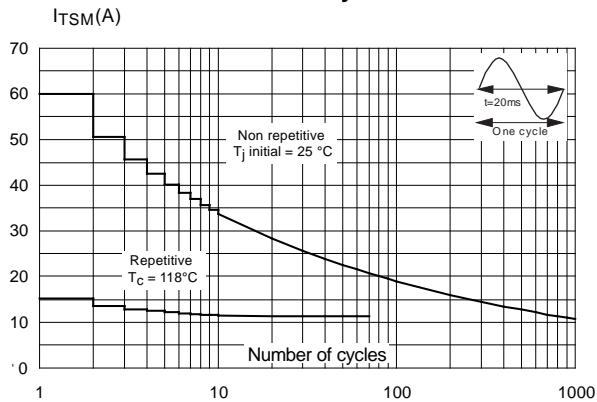
**Figure 6: Relative variation of gate trigger voltage and current versus junction temperature (typical values)**



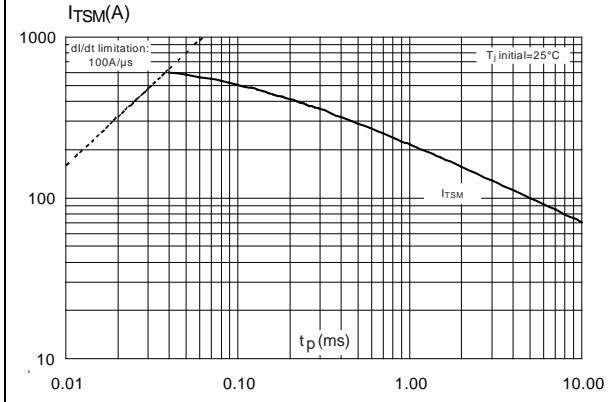
**Figure 7: Relative variation of holding current and latching current versus junction temperature (typical values)**



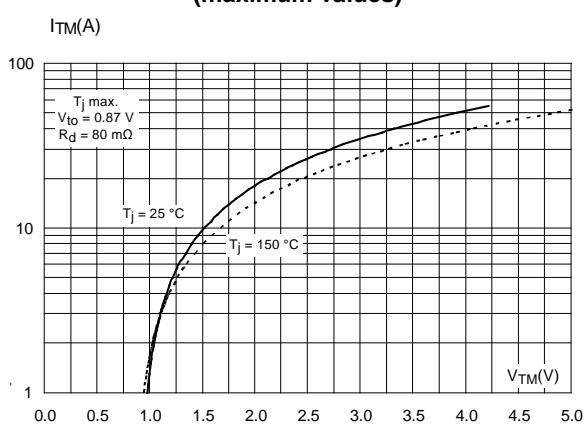
**Figure 8: Surge peak on-state current versus number of cycles**



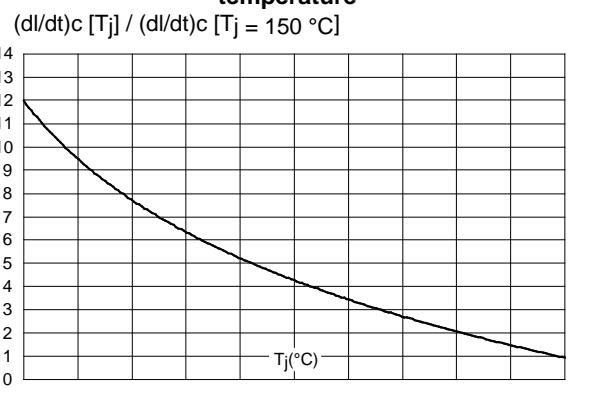
**Figure 9: Non repetitive surge peak on-state current for a sinusoidal pulse with width tp < 10 ms**



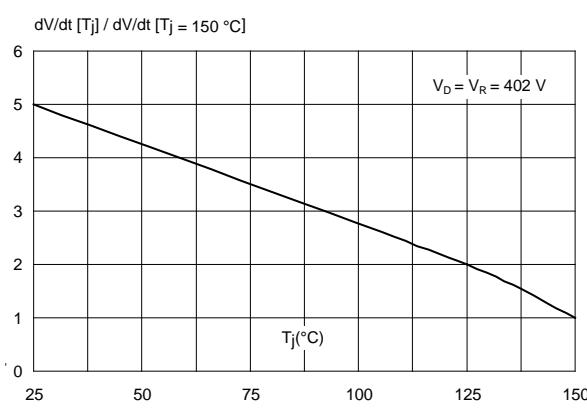
**Figure 10: On-state characteristics (maximum values)**



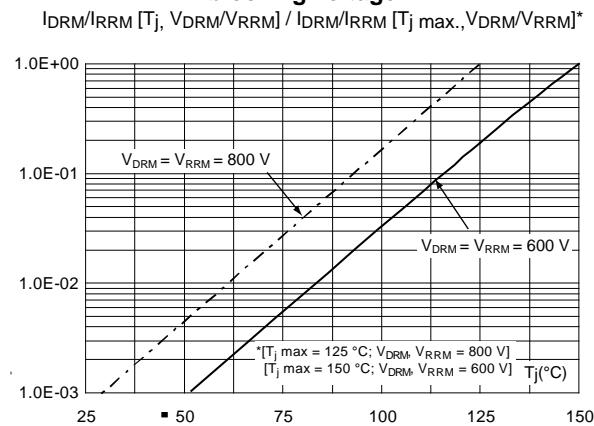
**Figure 11: Relative variation of critical rate of decrease of main current versus junction temperature**



**Figure 12: Relative variation of static dV/dt immunity versus junction temperature**



**Figure 13: Relative variation of leakage current versus junction temperature for different values of blocking voltage**



## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

- ECOPACK®2 (Lead-free plating and Halogen free package compliance)
- Lead-free package leads finishing
- Halogen-free molding compound resin meets UL94 standard level V0.
- Recommended torque (for through-hole package): 0.4 to 0.6 N·m

### 2.1 TO-220AB Insulated package information

Figure 14: TO-220AB Insulated package outline

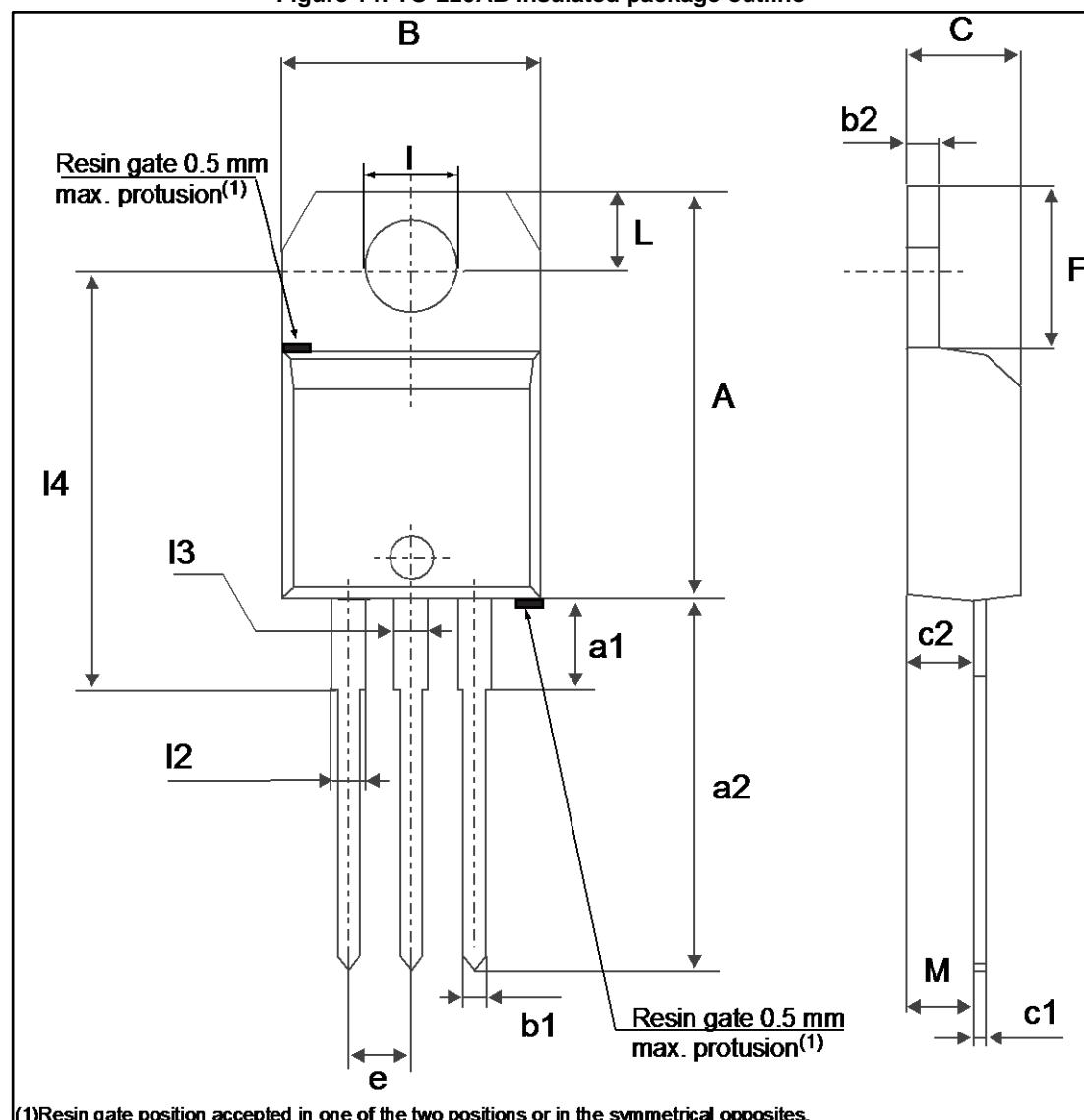


Table 6: TO-220AB Insulated package mechanical data

Ref.	Dimensions					
	Millimeters			Inches <sup>(1)</sup>		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	15.20		15.90	0.5984		0.6260
a1		3.75			0.1476	
a2	13.00		14.00	0.5118		0.5512
B	10.00		10.40	0.3937		0.4094
b1	0.61		0.88	0.0240		0.0346
b2	1.23		1.32	0.0484		0.0520
C	4.40		4.60	0.1732		0.1811
c1	0.49		0.70	0.0193		0.0276
c2	2.40		2.72	0.0945		0.1071
e	2.40		2.70	0.0945		0.1063
F	6.20		6.60	0.2441		0.2598
I	3.73		3.88	0.1469		0.1528
L	2.65		2.95	0.1043		0.1161
I2	1.14		1.70	0.0449		0.0669
I3	1.14		1.70	0.0449		0.0669
I4	15.80	16.40	16.80	0.6220	0.6457	0.6614
M		2.6			0.1024	

**Notes:**

(1)Inch dimensions are for reference only.

### 3 Ordering information

Figure 15: Ordering information scheme

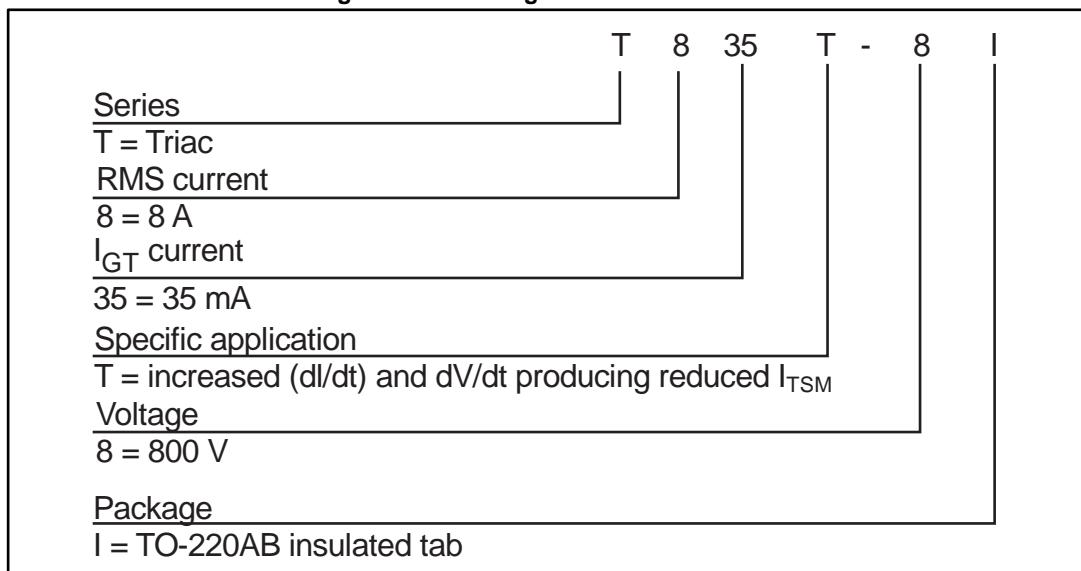


Table 7: Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
T835T-8I	T835T-8I	TO-220AB insulated	2.3 g	50	Tube

### 4 Revision history

Table 8: Document revision history

Date	Revision	Changes
17-Oct-2017	1	Initial release.
06-Nov-2017	2	Updated <a href="#">Table 4: "Static characteristics"</a> .

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